

# WAFER HANDLING SYSTEMS

967, 967L

Semi Auto Wafer Mounter



Crafted with the primary purpose of automatically affixing wafers onto tape, the ADT 967 Semi-Automatic Wafer Mounting System showcases a harmonious blend of intelligence and user-friendliness. This remarkable product holds significant value and is the ultimate selection for mounting during production processes.

## **Features & Benefits**

- Automatic- Controlled process, hands free operation
- Small footprint Tabletop design
- Quick and simple to use
- Minimal tape usage
- Flexible design supports a wide variety of tapes & frames
- Can be customized for multiple substrates (multi-panel) and irregular frames.

|                                 | 967                          | 967L               |
|---------------------------------|------------------------------|--------------------|
| Supported tapes                 | Dicing Blue-tapes / UV tapes |                    |
| Max. workpiece size             | 200mm (8")                   | 300mm (12")        |
| Supported film                  | DTF 2-8-1 ; DTF 2-6-1        | DTF-2-12           |
| frames                          | 350-103 ; 350-104            | SEMI-G74           |
| Temp Controlled Chuck<br>heater | < 65°c                       |                    |
| Roller pressure                 | 1-6 bar (adjustable)         |                    |
| Mounting time                   | 25 sec.                      | 35 sec.            |
| Machine dimensions<br>(WxDxH)   | 655 x 590 x 560 mm           | 791 x 706 x 557 mm |
| Approx. machine weight          | 65 kg                        | 85 kg              |

# **Options:**

- Non-Contact mounting
- · Electro-Static eliminator
- Rectangle frame support
- Auto frame size detector and cutter
- Top wafer surface lamination
- Communication and control features
- Special customized solutions

977, 977l

Wafer Cleaner

Streamlined and effective cleaning solutions to bolster your operations. The ADT 977 Wafer Cleaner Systems are meticulously crafted for the purpose of cleaning workpieces subsequent to the dicing process.



Equipped with adjustable rotating cleaning arm with atomizing or high pressure cleaning nozzles to cope with wide range of cleanliness requirements

#### **Features & Benefits**

- Atomizing/ High pressure cleaning
- Automatic lid closing
- Intuitive control panel
- Process monitoring
- Compact design
- Robust, vibration-free
- Environmentally friendly
- Programmable sequence control

|                                     | 977   | 977L                       |
|-------------------------------------|---|----------------------------|
| Max. workpiece size                 | Ø 8"  | Ø 12" or 12"x12"<br>square |
| Cleaning method                     | Atomizing cleaning / High pressure cleaning |                            |
| Number of recipes that can be saved | 20  |                            |
| Spinner velocity<br>range           | 200-3000 rpm                                | 200–2500 rpm               |
| Machine dimensions<br>(WxDxH)       | 410 x 625 x 946 mm                          | 570 x1250 x 1073 mm        |
| Approx. machine weight              | 120 kg                                      | 200 kg                     |

## **Options:**

- CO2 injection
- Water resistivity monitoring
- Ionizer
- Surfactant additional nozzle and tank
- Tape-less cleaning
- Built in exhaust blower
- Special customized solutions